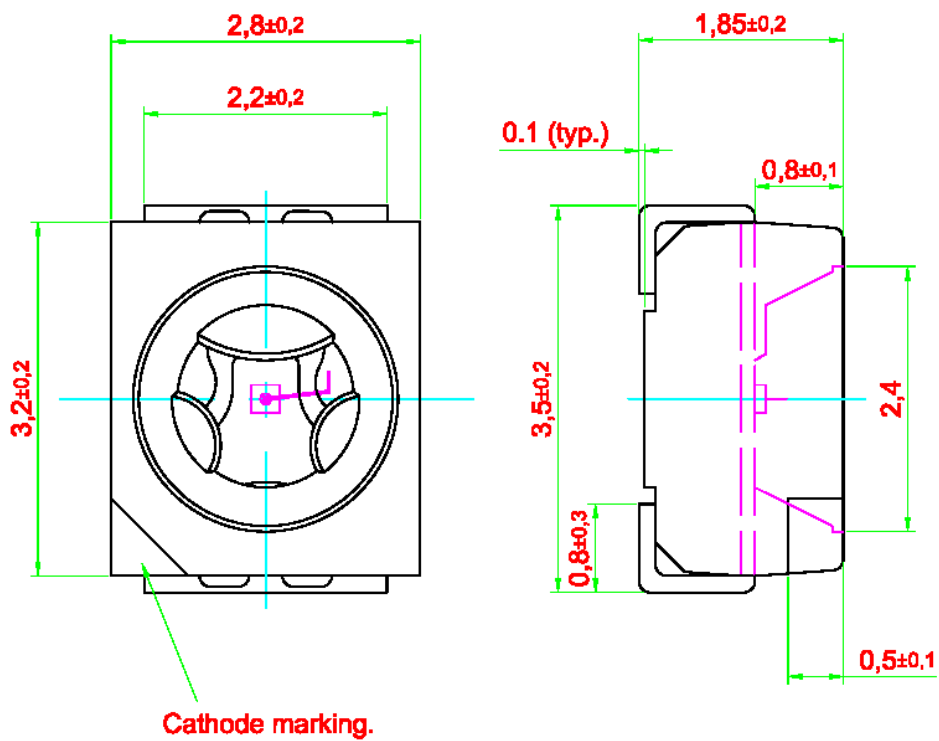




● **Feature:**

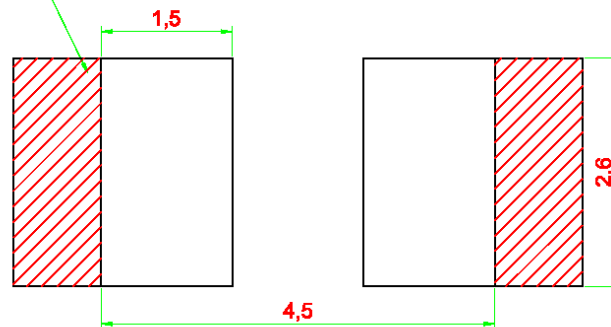
1. Surface mount LED.
2. 120° viewing angle.
3. Small package outline (LxWxH) of 3.2 x 2.8 x 1.8 mm.
4. Qualified according to JEDEC moisture sensitivity Level 2.
5. Compatible to both IR reflow soldering and TTW soldering.

● **Package Dimension:**



Recommended Solder Pad

Additional Cu area for improved heat dissipation.



 Solder resist.



● Optical Characteristics:

Part Number	Chip Technology / Color	Luminous Intensity @ If = 20mA Iv (mcd)
BL-PDR-GJS-C10 <ul style="list-style-type: none"> • BIN L1 • BIN L2 • BIN M1 • BIN M2 	GaP / Red, 625 nm	11.2 ... 28.5
BL-PDR-GJS-C20 <ul style="list-style-type: none"> • BIN M1 • BIN M2 • BIN N1 • BIN N2 		28.5 ... 71.5 11.2 ... 14.0 14.0 ... 18.0 18.0 ... 22.4 22.4 ... 28.5
BL-PDO-GJS-C10 <ul style="list-style-type: none"> • BIN L1 • BIN L2 • BIN M1 • BIN M2 	GaP / Orange, 605 nm	11.2 ... 28.5
BL-PDY-GJS-C10 <ul style="list-style-type: none"> • BIN L1 • BIN L2 • BIN M1 • BIN M2 		11.2 ... 28.5 11.2 ... 14.0 14.0 ... 18.0 18.0 ... 22.4 22.4 ... 28.5
BL-PDG-GJS-C20 <ul style="list-style-type: none"> • BIN L1 • BIN L2 • BIN M1 • BIN M2 	GaP / Green, 570 nm	11.2 ... 28.5
BL-PDG-GJS-C30 <ul style="list-style-type: none"> • BIN M1 • BIN M2 • BIN N1 • BIN N2 		18.0 ... 45.0 11.2 ... 14.0 14.0 ... 18.0 18.0 ... 22.4 22.4 ... 28.5 18.0 ... 22.4 22.4 ... 28.5 28.5 ... 35.5 35.5 ... 45.0

Forward voltage @ If=20 mA.	Chip Type	Viewing angle at 50% Iv	Reverse current, I _R @ V _R = 5V, (max)
2.2 V (typ.); 2.6 V (max)	GaP	120°	100 μA



NOTE:

1. Other luminous intensity groups are also available upon request.
2. Luminous intensity is measured with an accuracy of $\pm 11\%$.
3. Wavelength binning is carried for all units as per the wavelength-binning table. Only one wavelength group is allowed for each reel.
4. An optional Vf binning is also available upon request. Binning scheme is as per following table.

● **Absolute Maximum Ratings:**

Parameter	Maximum Value	Unit
DC forward current.	30	mA
Peak pulse current; ($t_p \leq 10 \mu s$, Duty cycle = 0.005)	500	mA
Reverse voltage.	5	V
LED junction temperature.	100	$^{\circ}C$
Operating temperature.	-40 ... +100	$^{\circ}C$
Storage temperature.	-40 ... +100	$^{\circ}C$
Power dissipation (at room temperature)	75	mW

● **Vf Binning:**

Vf Bin @ 20mA	Forward voltage (V)
01	1.55 ... 1.85
02	1.85 ... 2.15
03	2.15 ... 2.45
04	2.45 ... 2.60



● Wavelength Grouping:

Color	Group	Wavelength distribution (nm)
BL-PDR; Red	Full	620 – 635
BL-PDA; Amber	Full	610 – 621
	W	610 - 615
	X	615 - 621
BL-PDO; Orange	Full	600 – 612
	W	600 - 603
	X	603 - 606
	Y	606 - 609
	Z	609 - 612
BL-PDY; Yellow	Full	582 – 594
	W	582 – 585
	X	585 – 588
	Y	588 - 591
	Z	591 - 594
BL-PDG; Green	Full	564.5 – 576.5
	W	564.5 – 567.5
	X	567.5 – 570.5
	Y	570.5 – 573.5
	Z	573.5 – 576.5

Wavelength is measured with an accuracy of ± 1 nm.



● Typical electro-optical characteristics curves:

Fig. 1 Relative luminous intensity vs. forward current.

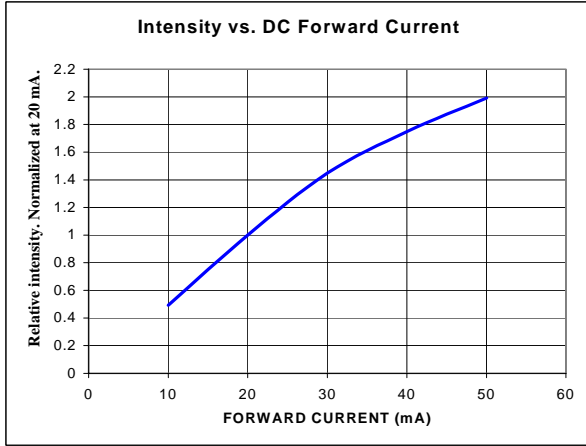


Fig. 2 Forward current vs. forward voltage.

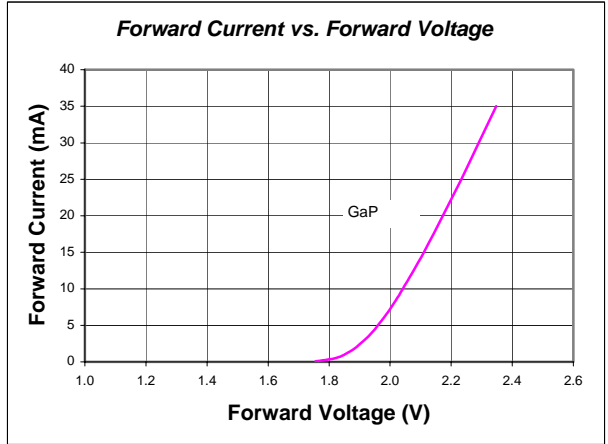


Fig. 3 Radiation pattern.

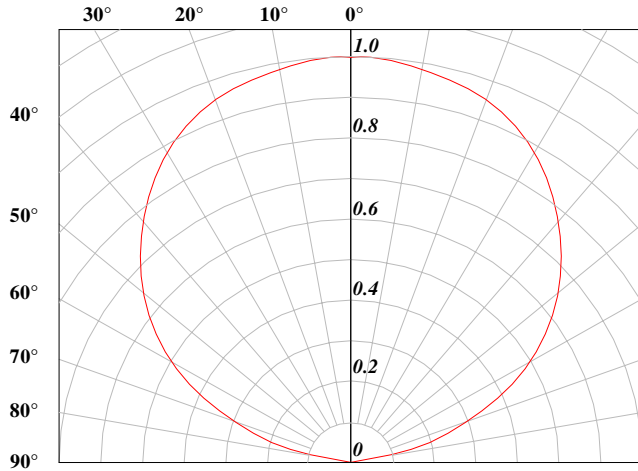


Fig. 4 Maximum forward current vs. temperature.

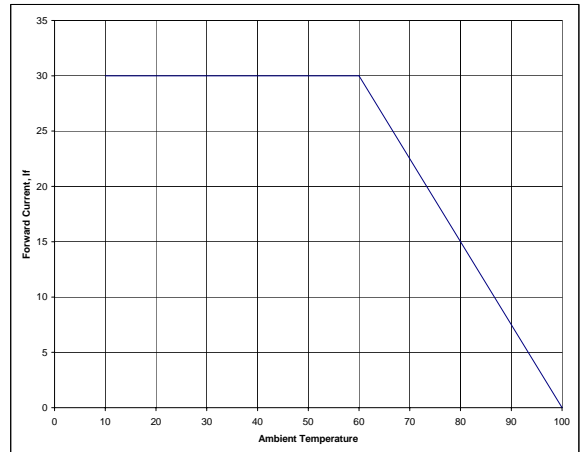




Fig. 5 Recommended IR-reflow Soldering Profile (acc. to IPC 9501)

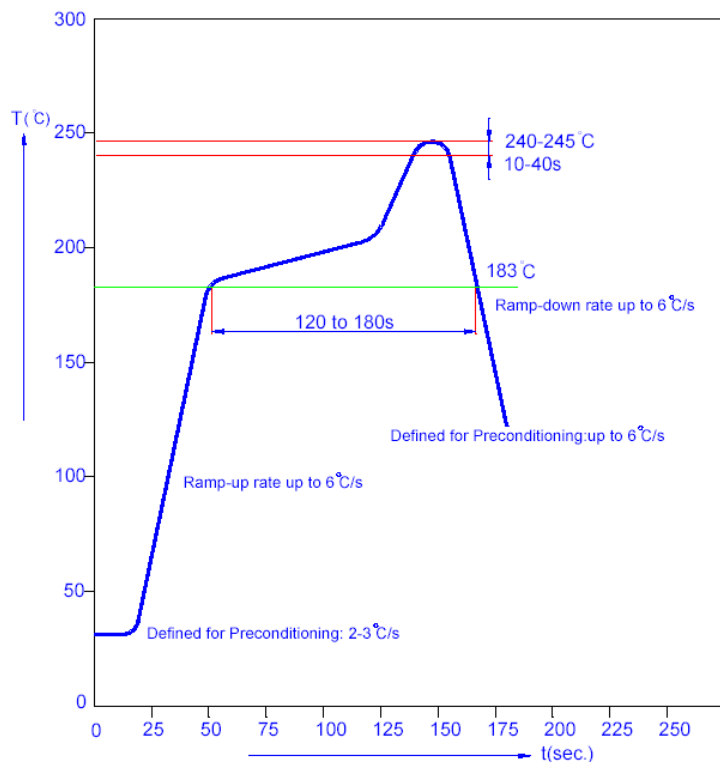
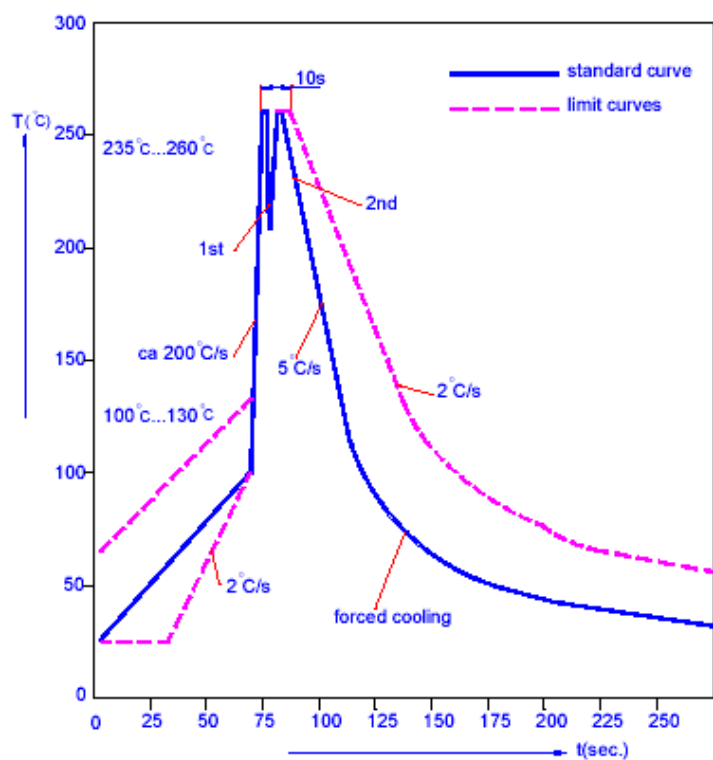


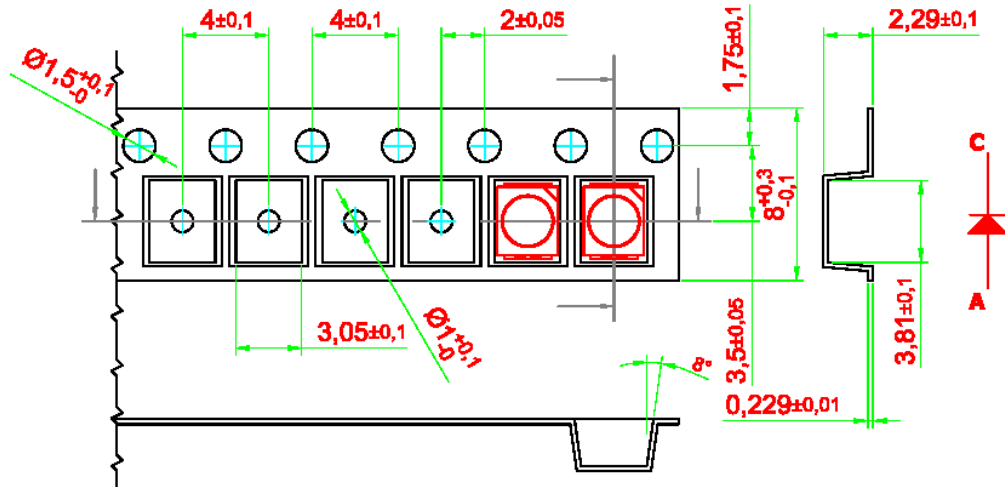
Fig. 6 Recommended TTW Soldering Profile (acc. to CECC 00802)





● Taping And Orientation:

Reels come in quantity of 2000 units. Reel diameters is 180 mm .



200 mm min. for $\varnothing 180$ reel.

480 mm min. for $\varnothing 180$ reel.

200 mm min. for $\varnothing 330$ reel.

960 mm min. for $\varnothing 330$ reel.

